SEMICONDUCTOR WAFER PROCESSING TAPE WINDING BODY, SEMICONDUCTOR WAFER PROCESSING TAPE STICKING APPARATUS AND SEMICONDUCTOR WAFER PROCESSING APPARATUS THAT USE THE SEMICONDUCTOR WAFER PROCESSING TAPE WINDING BODY

ABSTRACT OF THE DISCLOSURE

It is an object to provide a semiconductor wafer processing tape sticking apparatus capable of sticking a semiconductor wafer processing tape to a semiconductor wafer under the optimum conditions based on the processing data that has been written to a data carrier member and that has been read from the data carrier member without accessing the host computer unlike a conventional method.

The semiconductor wafer processing tape sticking apparatus is characterized by comprising:

a feeding apparatus provided with a feeding shaft to which a semiconductor wafer processing tape winding body can be detachably attached,

a tape data read/write device for reading and writing the processing data that has been written to a data carrier member of the semiconductor wafer processing tape winding body, and

a tape sticking apparatus for sticking a semiconductor wafer processing tape that has been fed out from the feeding apparatus to the semiconductor wafer based on the processing data that has been read by the tape data read/write device.